



SO DIFFERENT

如此与众不同
只因我们专注

专注于焊锡制品的
研发和生产





2014	\$ 3+ Million	1000+ m ²
FOUND	ASSET	PLANT AREA
6 Pcs	\$ 14 Million	30
PRODUCT LINE	ANNUAL VALUE	STAFF

We were established in 2014 and specializes in the development, production, and sales of electronic soldering materials, integrating research and development with market promotion. The company has total assets exceeding 20 million yuan and an annual output value of 100 million yuan. We have a dedicated team of over 30 employees, and our factory covers more than 1,000 square meters.

We has obtained ISO 9001:2015 certification for its quality management system, ISO 14001:2015 certification for its environmental management system, as well as certifications from authoritative domestic and international quality inspection organizations, including SGS and MSDS.

We take pride in our in-house research and development team, composed of highly qualified management professionals and experienced soldering technology experts with over a decade of expertise. Our team is committed to innovation and works closely with renowned brands, building a strong reputation in the soldering industry in Shanghai through long-term and proactive engagement.

We consistently uphold our core values of "Integrity, Pragmatism, Innovation, and Efficiency," adhering to the principle of operating with honesty and promoting our corporate spirit of "Surpassing Ourselves and Committing to Innovation." In our production and operational activities, we follow the principle of "Quality-driven Production and Reputation-driven Development." We maintain strict quality control over our raw materials to ensure the reliability and competitiveness of our products, which have gained recognition in China, Southeast Asia, and Europe.



PARTIAL PARTNERS



电子制造
用于连接电子元件如智能手机、计算机、路由器等通讯设备的电子元件焊接

E-MAKE



光电照明
用于LED和其他照明设备的电子组装

Illumination



医疗设备
在心电图机、监护仪等医疗电子设备中，焊锡确保关键电气连接的可靠性

Armarium



航空航天
用于航空航天设备和系统中的电子连接，要求极高的可靠性和耐用性

Aerospace



半导体
用于半导体芯片附着，引线链接和封装组装等

Semiconductor

APPLICATION FIELD

EDO 和辉光电

LCE
联创电子

WULING

GREE 格力

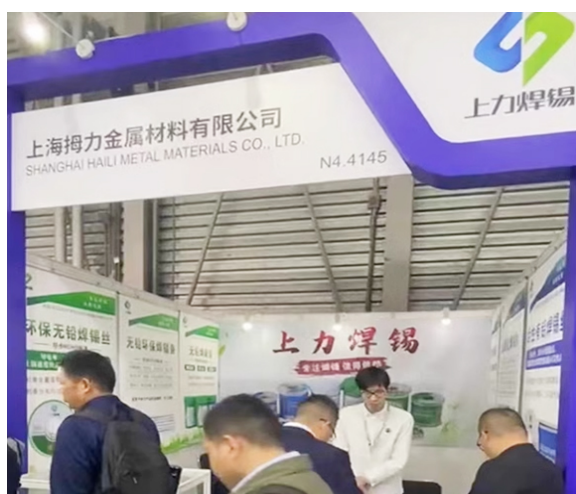
SIEMENS Healthineers



FACTORY DISPLAY



EXHIBITION DISPLAY

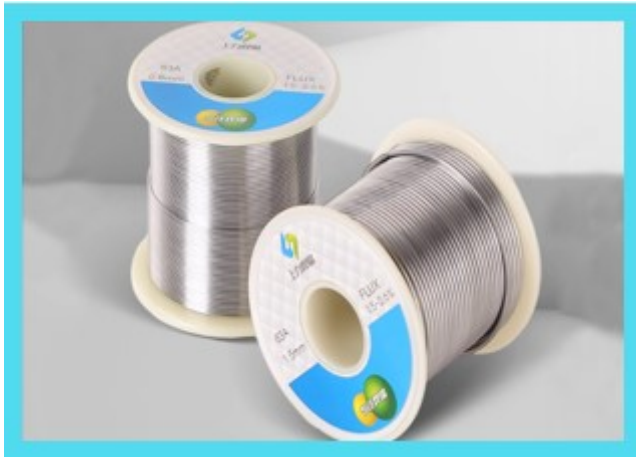


SOLDER WIRE



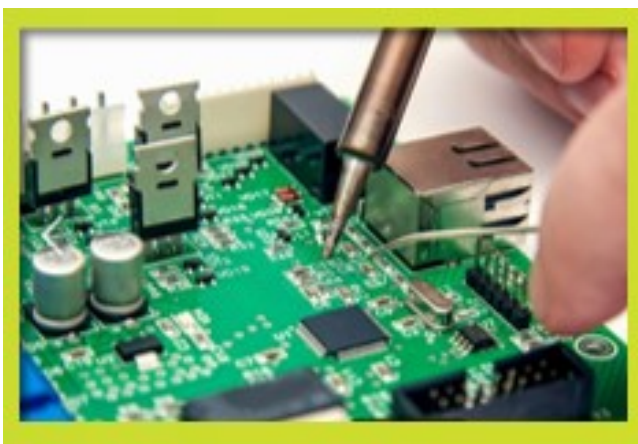
Automatic Soldering Of Solder Wire

Meet the needs of mass production in automatic welding process. Compatible with various brands of automatic welding machine, suitable for machine welding, drag welding and manual welding and other processes, excellent wettability, fast welding and curing speed, bridge, pull point, less smoke, can effectively inhibit solder and flux splash, residue can be free to clean (except special products).



Rosin Cored Solder Wire

The rosin core flux is divided into three types: R type (rosin flux), RMA type (weak active rosin flux) and RA type (active rosin resin flux). This kind of product has the characteristics of fast welding speed, less splash, bright solder joint and wide use.



Solder wire for capacitors

Applied to the capacitor manufacturing industry, the high activity solder wire can be welded directly on the end face of the capacitor zinc spray layer and the low melting point gold spray alloy layer. It has the characteristics of fast welding speed, fast melting, bright, strong welding point, etc.

In addition: color lamp soldering wire/stainless steel soldering wire/wash tin wire/solid tin wire/high temperature tin wire/low temperature tin wire/nickel plated tin wire, etc.,

Various specifications and various tin alloy content are available for customers to choose from.

类别 Item	规格 Spec.	合金成分 Alloy Composition/WT%	熔点 °C Melting	线径 Diaø	用途 Application	
Lead solder wire	63A Tin Wire	Sn63-Pb37	183°	8.4g	0.3-3mm	Relatively high requirements: high precision instruments, electronics Industrial, circuit board (high requirements), communication, micro technology, aviation industry and other welding.
	1# Tin Wire	Sn60-Pb40	183° -190°	8.5g	0.5-3mm	
	2# Tin Wire	Sn55-Pb45	183° -203°	8.7g	0.5-3mm	
	3# Tin Wire	Sn50-Pb50	183° -216°	8.9g	0.8-3mm	Relatively common requirements: home appliances, electrical instruments, General requirements for circuit board) Welding of automotive electrical appliances, general hardware electrical appliances, etc.
	4# Tin Wire	Sn45-Pb55	183° -227°	9.0g	0.8-3mm	
	5# Tin Wire	Sn40-Pb60	183° -238°	9.3g	0.8-3mm	
	6# Tin Wire	Sn35-Pb65	183° -247°	9.5g	0.8-3mm	
	7# Tin Wire	Sn30-Pb70	183° -255°	9.7g	0.8-3mm	
	8# Tin Wire	Sn25-Pb75	183° -266°	9.9g	0.8-3mm	

类别 Item	合金成分 Alloy Composition/WT%	熔点 °C Melting	密度 Density	用途 Application
无铅环保焊锡丝 Lead-free environment-friendly soldering wire	Sn99.3/Cu0.7	227°	7.4	Suitable for high-end electronic products, export quality electronic, electrical industrial products
	Sn99Ag0.3Cu0.7	221°	7.37	
	Sn96.5Ag3.0Cu0.5	217°	7.37	

SOLDER BAR



Low Temperature Solder Bar

70°C-180°C various low melting point alloy material products. It is widely used in: fire alarm safety devices, lightning protection devices, lightning protection devices, air conditioning safety protectors, temperature indicating materials, mechanical processing fillers and other industries.



Silver Containing Solder Bar

The addition of silver can improve the fluidity, wettability and oxidation resistance of welding alloys, provide more reliable welding connections, especially in the welding of electronic components and high-precision equipment, and can significantly improve the quality of solder joints. SAC305 and SAC307 are standard products.



Wave Soldering Bar

Welding materials specially designed for the wave crest welding process. In the wave soldering process, the solder strip will be heated and melted, and then form a wave peak, and when the PCB passes through this wave peak, the solder will be combined with the welding point to form a strong electrical connection.

In addition: anti-oxidation solder bars and other uses of solder bars, can provide a variety of specifications and various tin alloy content customization.

类别 Item	合金成分 Alloy Composition/WT%	熔点 °C Melting	密度 Density	用途 Application
LEAD SOLDER BAR	Sn63-Pb37	183°	8.4g	Relatively high requirements: high precision instruments, electronics Industrial, circuit board (high requirements), communication, micro technology, aviation industry and other welding.
	Sn60-Pb40	183° -190°	8.5g	
	Sn55-Pb45	183° -203°	8.7g	
	Sn50-Pb50	183° -216°	8.9g	Relatively common requirements: home appliances, electrical instruments, General requirements for circuit board)
	Sn45-Pb55	183° -227°	9.0g	
	Sn40-Pb60	183° -238°	9.3g	Welding of automotive electrical appliances, general hardware electrical appliances, etc.
	Sn35-Pb65	183° -247°	9.5g	Relatively Pricerite requirements: general mechanical welding, car water tank, light bulbs, cable joints and other welding.
	Sn30-Pb70	183° -255°	9.7g	
	Sn25-Pb75	183° -266°	9.9g	

类别 Item	合金成分 Alloy Composition/WT%	熔点 °C Melting	密度 Density	用途 Application
Lead-free environmentally friendly solder bar	Sn99.3/Cu0.7	227°	7.4	Suitable for high-end electronic products, export quality electronic, electrical industrial products
	Sn99Ag0.3Cu0.7	221°	7.37	
	Sn96.5Ag3.0Cu0.5	217°	7.37	
	Sn99.95 (纯锡) -Pure Tin	232°	7.41	It is suitable for all kinds of circuit board electroplating and for reducing copper content in tin furnaces with excessive copper content

SOLDER PASTE

Lead solder paste



Meet the needs of mass production in automatic welding process. Compatible with various brands of automatic welding machine, suitable for machine welding, drag welding and manual welding and other processes, excellent wettability, fast welding and curing speed, bridge, pull point, less smoke, can effectively inhibit solder and flux splash, residue can be free to clean (except special products).

Eco-friendly lead-free solder paste



Good wettability, not easy to dry, easy to operate, stable printability, minimal viscosity change during continuous printing, no collapse, patch components will not offset, as low as 0.3mm spacing pad can also complete exquisite printing, surface insulation impedance is high, to solve the problem of dense IC tin, tin bead, virtual welding and other problems

Semiconductor Solder Paste



Solder paste specially formulated for the grain adhesion process. This product has been carefully prepared, using automatic dispensing equipment to provide a stable amount of solder paste, reliable performance. Semiconductor high temperature and high lead solder paste is used for reflow soldering in nitrogen environment, leaving a completely harmless residue, which only accounts for 2% of the solder paste mass.

Additionally, we distribute well-known solder paste brands both domestically and internationally and welcome inquiries for pricing.

规格 Spec.	合金成分 Alloy Composition/WT%	熔点 °C Melting	颗粒 Particle	重量 Weight	适用 Apply	特点 Characteristic
55/45-3 # Powder	Sn55% Pb45%	190°	25-45 micron	500g/can	LED bead SMT	LED lights do not shift easily
60/40-3 # Powder	Sn60% Pb40%	190°	25-45 micron	500g/can	LED bead SMT	Solder joint is bright. Shaolian tin
63/37-3 # Powder	Sn63% Pb37%	183°	25-45 micron	500g/can	Normal STM	Strong tin, less tin, bright and full solder joint
63/37-4 # Powder	Sn63% Pb37%	183°	20-38 micron	500g/can	Polypod patch	Particle is small, the tin is strong, the solder joint is bright and full
有铅含银-4 # Powder silver in lead	Sn62.9 Pb36.9 Ag0.2	183°	20-38 micron	500g/can	QFN mounting	Good wettability, climbing tin fast, less tin beads, high reliability
有铅高含银-4 # Powder High rate silver in lead	Sn62.8 Pb36.8 Ag0.4	183°	20-38 micron	500g/can	BGA chip tinning	Good wettability, strong climbing tin, good electrical conductivity, round and bright solder joints

规格 Spec.	合金成分 Alloy Composition/WT%	熔点 °C Melting	颗粒 Particle	重量 Weight	适用 Apply	特点 Characteristic
无铅低温焊锡膏 Lead-free low temperature solder paste	Sn42%/Bi58%	138°	20-38 micron	500g/can	LED	低温 上锡强 焊点光亮 Low temperature tin strong solder joint bright
无铅中温焊锡膏 Lead-free medium temperature solder paste	Sn64.7Bi35Ag0.3	183°	20-38 micron	500g/can	High demand product	无铅环保, 爬锡强, 连锡少 Lead-free environmental protection, climbing tin strong, even tin less
无铅中温焊锡膏 Lead-free medium temperature solder paste	Sn64Bi35Ag1	183°	20-38 micron	500g/can	High demand product	无铅环保, 爬锡强, 连锡少 Lead-free environmental protection, climbing tin strong, even tin less
无铅高温焊锡膏 Lead-free high temperature solder paste	Sn99Ag0.3Cu0.7	217°	20-38 micron	500g/can	High demand product	无铅环保, 润湿性好, 爬锡快, 少锡珠, 可靠性高 Lead-free environmental protection, good wettability, climbing tin fast, less tin beads, high reliability

锡球

- 环保无铅99.9%纯锡球
- 纯度高、锡渣少、焊点光亮
- 优良的润湿性和可焊性、生产效率高
- 适用于各种焊锡作业方式
- 外观洁净、光亮.无污染物



红胶

· 红胶是单一组分常温储藏受热后迅速固化的环氧树脂胶粘剂，其容许低温固化，其“剪切稀化”粘度特性和低吸湿性，适合应用于常温孔版印刷的SMT工艺，胶点形状非常容易控制，储存稳定且具有优良的耐热冲击性能和电气性能。



助焊剂

- 含卤素低，电绝缘性可靠；
- 树脂含量低，焊后几乎无残留物且清洁度好；
- 表面张力适中，可焊性好，焊点饱满光亮；
- 烟雾小，无刺激性气味，对人体健康无危害。

